YES-ÉcoClean
Automated Plasma Photoresist Strip/Descum System

Powerful, Damage-Free Cleaning Removes Photoresist, Polyimide and BCB

Specifications

Hardware	
Clean Room Compatibility	Class 10
Hot Plate Temperature Range	50º to 300 °C
Capacity	Single wafer/2”-200mm/silicon, GaAs, sapphire, ceramic
Pins up/Pins down process mode	Pins up or down for process flexibility
Throughput	≥ 50 wph/ 4µ photoresist/ 250°C process
Process Gas Inputs	2 MFCs standard (Oxygen and Nitrogen), 3rd forming gas MFC optional
Process Chamber Dimensions	33.02 cm (W) x 30.50 cm (D) x 15.24 cm (H) (13” x 12” x 6”)
Hot Plate Process Area	49 in^2 maximum (200mm wafer)
Wafer Handling Robot	Single arm, surface-mount design 7.25” Z travel/ 50-200mm wafers Multiple end effectors are available for various substrates and materials
Overall System Dimensions	50.8 cm (W) x 144.4(D) x 171.4 cm (H) (20" x 56.85" x 67.48")
Chamber Material	6061-T6 aluminum
Compliance	SEMI S2, S8
Software	
User Interface	PC with touch screen monitor and pull-out keyboard, barcode reader
Number of Recipes	File-based data collection
SECS/GEM	Optional
Performance	
Descum Specifications	
• Estimated Throughput	Up to 65 wph @ 10 second process
• Approx. Ash Rate	100-2000Å/ min
• Uniformity	Within Wafer: +/- 10% Wafer to Wafer: +/- 10% Lot to Lot: +/- 10%
Photoresist Strip Rate	
• Strip Rate	Up to 10 µm/min @250°C
• Handling Speed	15-30 sec process= 50-60 wph
• Uniformity 200 mm (Silicon)	Within Wafer: +/- 10% Wafer to Wafer: +/- 10% Lot to Lot: +/- 10%
Additional	
Power Requirements	208 VAC 4-wire 3PH, 50/60 Hz, 30 Amps
• RF Power Supply	RF Automatic, fully-contained, water-cooled system
• Requires chilled water	For chamber and plasma source
• Requires vacuum pump	200-350 CFM vacuum pump
Compliance	CE, UL, CSA, Korea

Contact Us

Please call us to run a process demonstration. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at www.yieldengineering.com.

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